

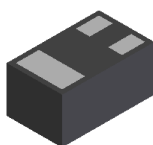
Features

- Epitaxial Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ultra-low Profile (0.40mm max)
- Complementary NPN Type Available (DN0150ALP4 / DN0150BLP4)
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free, "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

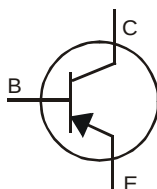
Mechanical Data

- Case: DFN1006H4-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0008 grams (approximate)

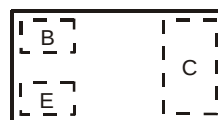
DFN1006H4-3



Bottom View



Device Symbol

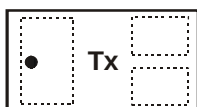

 Top View
 Device Schematic

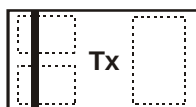
Ordering Information (Note 3)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DP0150ALP4-7	T5	7	8	3,000
DP0150ALP4-7B	T5	7	8	10,000
DP0150BLP4-7	T6	7	8	3,000
DP0150BLP4-7B	T6	7	8	10,000

- Notes:
1. No purposefully added lead.
 2. Diodes Inc's "Green" policy can be found on our website at <http://www.diodes.com>
 3. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information

 DP0150ALP4-7
 DP0150BLP4-7

 Top View
 Dot Denotes
 Collector Side

 DP0150ALP4-7B
 DP0150BLP4-7B

 Top View
 Bar Denotes Base
 and Emitter Side

Tx = Product Type Marking Code
 T5 = DP0150ALP4
 T6 = DP0150BLP4

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-50	V
Emitter-Base Voltage	V _{EBO}	-5	V
Collector Current - Continuous	I _C	-100	mA
Peak Pulse Collector Current	I _{CM}	-200	mA
Base Current	I _B	-30	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P _D	450	mW
Thermal Resistance, Junction to Ambient (Note 4)	R _{θJA}	278	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-50	—	—	V	I _C = -10μA, I _E = 0
Collector-Emitter Breakdown Voltage (Note 5)	V _{(BR)CEO}	-50	—	—	V	I _C = -1mA, I _B = 0
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5	—	—	V	I _E = -10μA, I _C = 0
Collector Cut-Off Current	I _{CBO}	—	—	-0.1	μA	V _{CB} = -50V, I _E = 0
Emitter Cut-Off Current	I _{EBO}	—	—	-0.1	μA	V _{EB} = -5V, I _C = 0
ON CHARACTERISTICS (Note 5)						
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	-0.15	-0.3	V	I _C = -100mA, I _B = -10mA
DC Current Gain	DP01510ALP4	120	—	240	—	V _{CE} = -6V, I _C = -2mA
	DP01510BLP4	200	—	400		
SMALL SIGNAL CHARACTERISTICS						
Transition Frequency	f _T	80	—	—	MHz	V _{CE} = -10V, I _E = 1mA f = 30MHz
Output Capacitance	C _{ob}	—	1.6	—	pF	V _{CB} = -10V, I _E = 0, f = 1MHz

Notes: 4. Device mounted on FR-4 PCB with minimum recommended pad layout.
5. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤2%

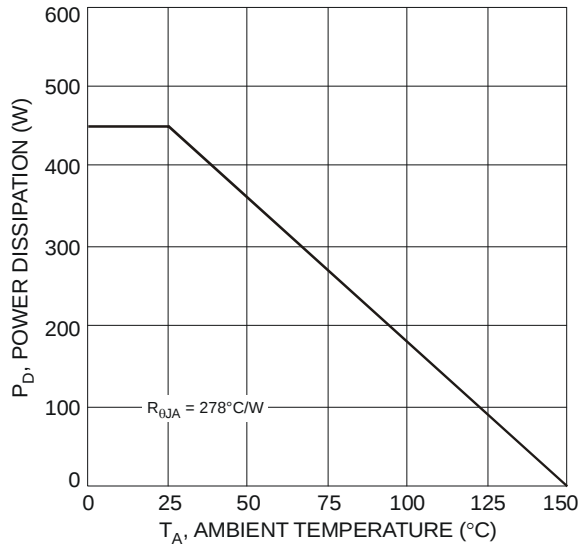


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)

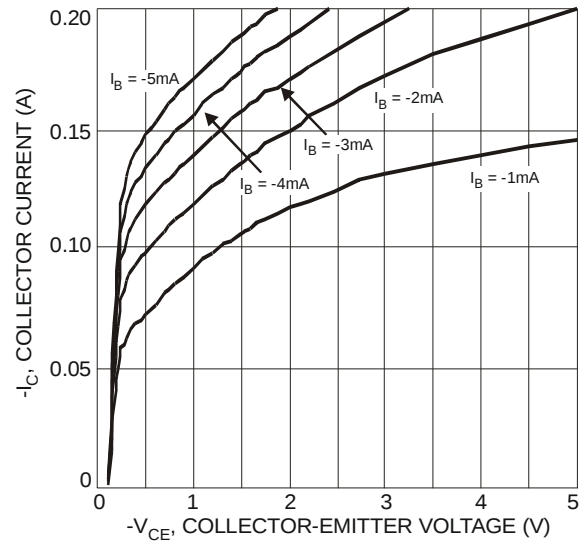


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage (DN0150BLP4)

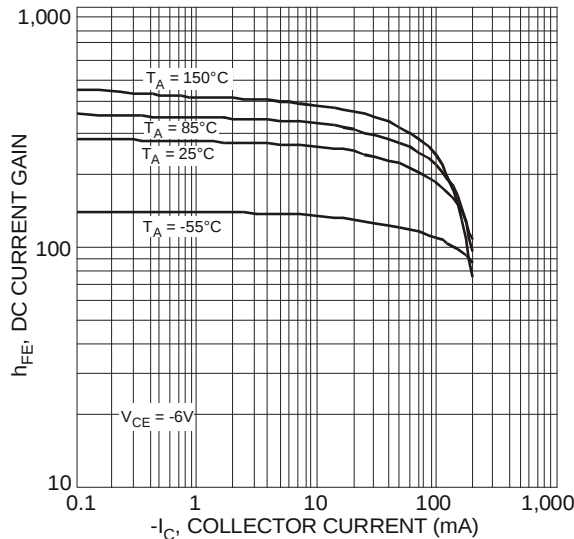


Fig. 3 Typical DC Current Gain vs. Collector Current (DN0150BLP4)

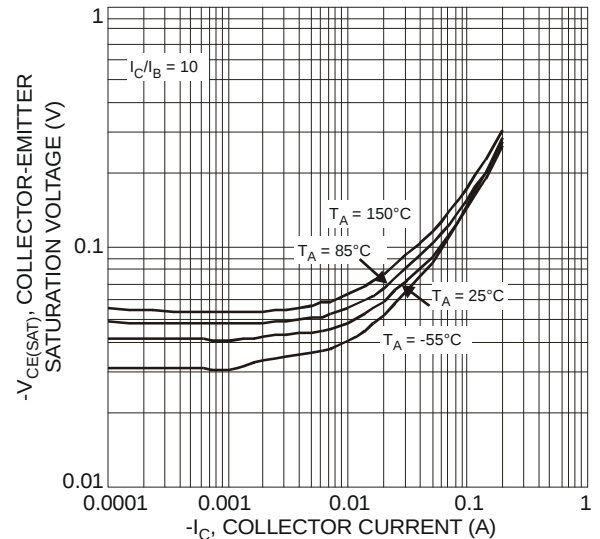


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

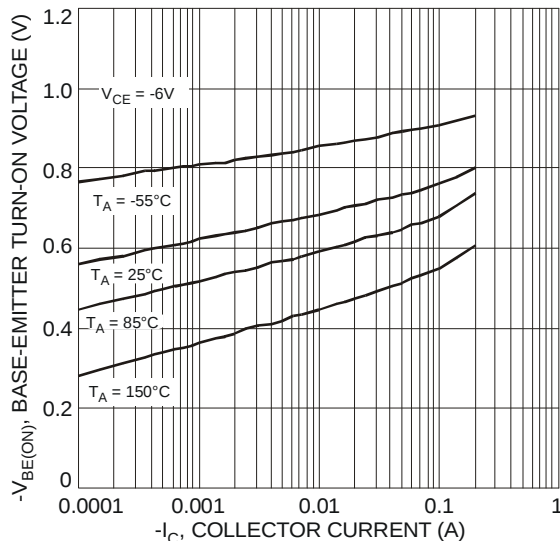


Fig. 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

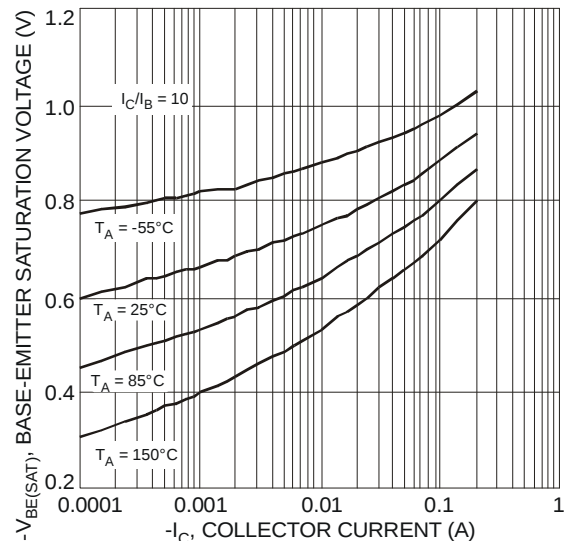


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

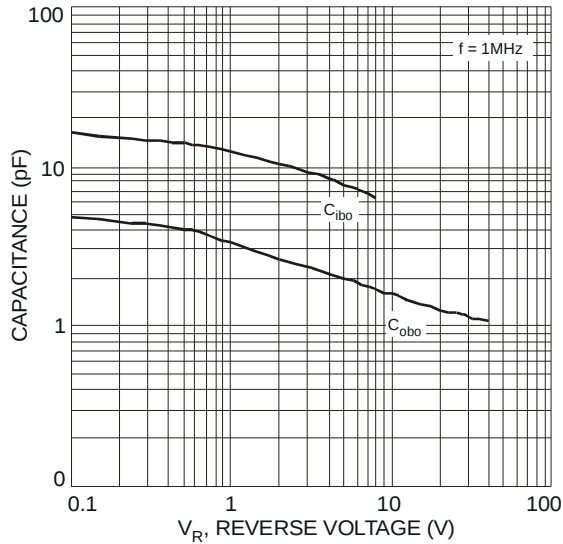


Fig. 7 Typical Capacitance Characteristics

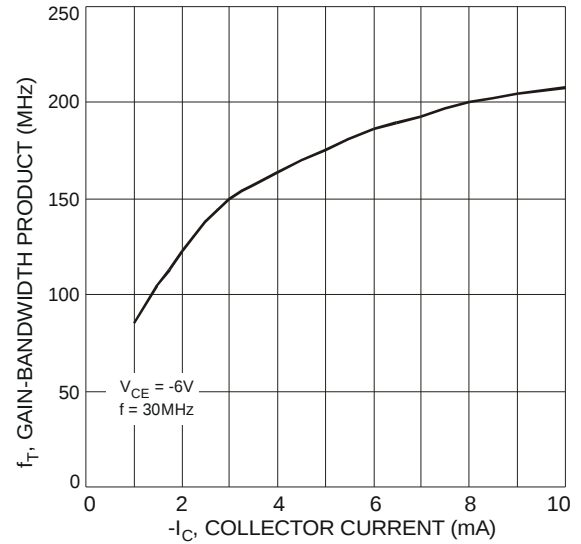
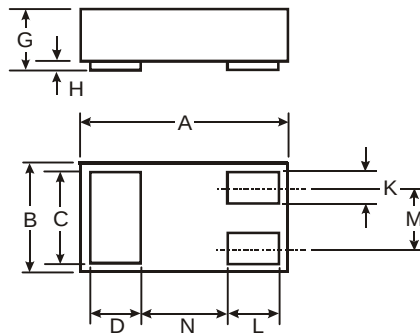


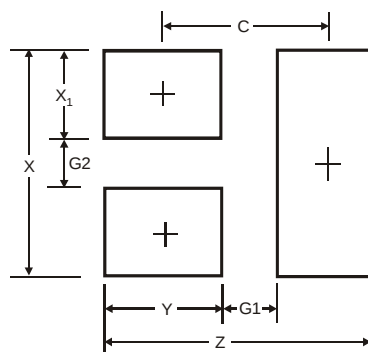
Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions



DFN1006H4-3			
Dim	Min	Max	Typ
A	0.95	1.075	1.00
B	0.55	0.675	0.60
C	0.45	0.55	0.50
D	0.20	0.30	0.25
G	—	0.40	—
H	0	0.05	0.02
K	0.10	0.20	0.15
L	0.20	0.30	0.25
M	—	—	0.35
N	—	—	0.40
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

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